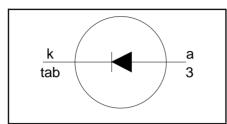
BYC10B-600

FEATURES

- Extremely fast switching
- Low reverse recovery current
- · Low thermal resistance
- Reduces switching losses in associated MOSFET

SYMBOL



QUICK REFERENCE DATA

$$V_R = 600 \text{ V}$$
 $V_F \le 1.8 \text{ V}$
 $I_{F(AV)} = 10 \text{ A}$
 $t_{rr} = 19 \text{ ns (typ)}$

APPLICATIONS

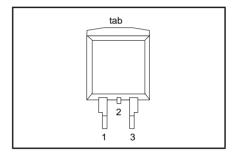
- Active power factor correction
- Half-bridge lighting ballastsHalf-bridge/ full-bridge switched mode power supplies.

The BYC10B-600 is supplied in the SOT404 surface mounting package.

PINNING

PIN	DESCRIPTION	
1	no connection	
2	cathode ¹	
3	anode	
tab	cathode	

SOT404



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{RRM}	Peak repetitive reverse voltage		-	600	V
V _{RWM}	Crest working reverse voltage		-	600	V
V _R	Continuous reverse voltage	$T_{mb} \le 114 ^{\circ}C$	-	500	V
I _{F(AV)}	Average forward current	$\delta = 0.5$; with reapplied $V_{RRM(max)}$; $T_{mb} \le 78 ^{\circ}C$	-	10	Α
I _{FRM}	Repetitive peak forward current	$\delta = 0.5$; with reapplied $V_{RRM(max)}$; $T_{mb} \le 78 ^{\circ}C$	-	20	Α
I _{FSM}	Non-repetitive peak forward	t = 10 ms	-	65	A
1 0111	current.	t = 8.3 ms	-	71	Α
		sinusoidal; $T_j = 150^{\circ}C$ prior to surge with reapplied $V_{RWM(max)}$			
T _{stg}	Storage temperature	FT Kwiwi(max)	-40	150	°C
T _j	Operating junction temperature		-	150	°C

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R _{th j-mb}	Thermal resistance junction to mounting base		-	-	2	K/W
R _{th j-a}		minimum footprint, FR4 board	-	50	-	K/W

¹ it is not possible to make connection to pin 2 of the SOT404 package

BYC10B-600

ELECTRICAL CHARACTERISTICS

T_i = 25 °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _F	Forward voltage	I _F = 10 A; T _i = 150°C I _F = 20 A; T _i = 150°C	-	1.4	1.8	V
		$I_F = 20 \text{ A}; T_j = 150^{\circ}\text{C}$	-	1.7	2.3	V
l	Reverse current	$ \vec{l}_{F} = 10 \text{ A};$ $ \vec{V}_{R} = 600 \text{ V}$	-	2.0 9	2.8 200	ν Λ
I _R	Reverse current	$V_R = 600 \text{ V}$ $V_R = 500 \text{ V}$; $T_i = 100 \text{ °C}$	-	1.1	3.0	μA mA
t _{rr}	Reverse recovery time	$I_F = 1 \text{ A}; V_R = 30 \text{ V}; dI_F/dt = 50 \text{ A/}\mu\text{s}$	-	35	55	ns
t _{rr}	Reverse recovery time	$I_F = 10 \text{ A}; V_R = 400 \text{ V};$	-	19	-	ns
t _{rr}	Reverse recovery time	$dI_{F}/dt = 500 A/\mu s$ $I_{F} = 10 A; V_{R} = 400 V;$ $dI_{F}/dt = 500 A/\mu s; T_{j} = 125 C$	-	32	40	ns
I _{rrm}	Peak reverse recovery current	$I_F = 10 \text{ A}; V_R = 400 \text{ V};$ $dI_F/dt = 100 \text{ A}/\mu\text{s}; T_i = 125^{\circ}\text{C}$	-	3	7.5	Α
I _{rrm}	Peak reverse recovery current	$I_F = 10 \text{ A}/\mu\text{s}, \ I_i = 125 \text{ C}$ $I_F = 10 \text{ A}; \ V_R = 400 \text{ V};$ $I_F = 125 \text{ C}$ $I_F = 125 \text{ C}$	-	9.5	12	А
V_{fr}	Forward recovery voltage	$I_F = 10 \text{ A}; dI_F/dt = 100 \text{ A/}\mu\text{s}$	-	8	11	V

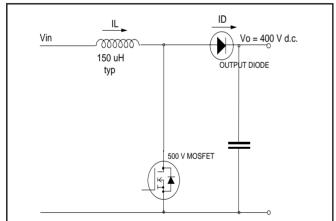


Fig.1. Typical application, output rectifier in boost converter power factor correction circuit. Continuous conduction, mode where the transistor turns on whilst forward current is still flowing in the diode.

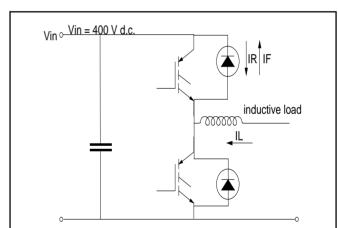


Fig.2. Typical application, freewheeling diode in half bridge converter. Continuous conduction mode, where each transistor turns on whilst forward current is still flowing in the other bridge leg diode.

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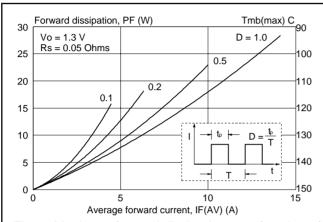


Fig.3. Maximum forward dissipation as a function of average forward current; rectangular current waveform where $I_{F(AV)} = I_{F(RMS)} \times \sqrt{D}$.

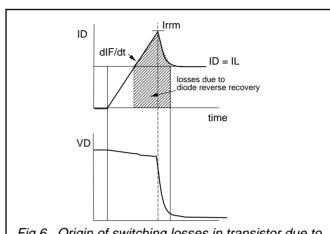


Fig.6. Origin of switching losses in transistor due to diode reverse recovery.

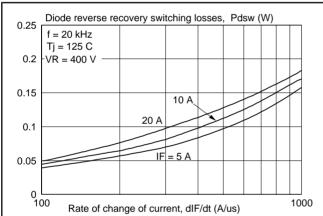


Fig.4. Typical reverse recovery switching losses in diode, as a function of rate of change of current dl_e/dt.

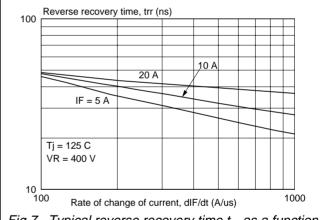


Fig.7. Typical reverse recovery time t_{rr}, as a function of rate of change of current dl_r/dt.

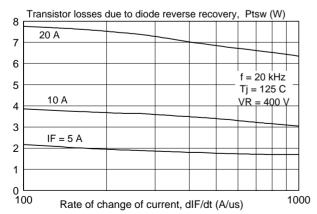


Fig.5. Typical switching losses in transistor due to reverse recovery of diode, as a function of of change of current dl /dt.

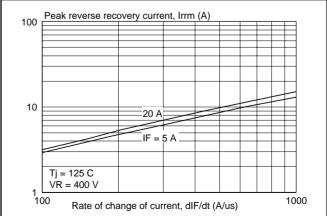
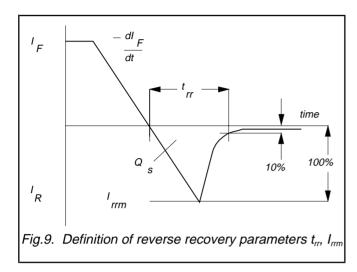


Fig.8. Typical peak reverse recovery current, I_{rrm} as a function of rate of change of current dI_F/dt .

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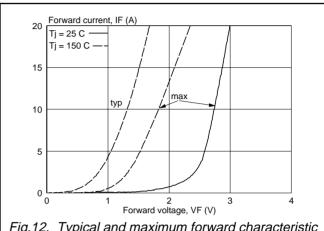
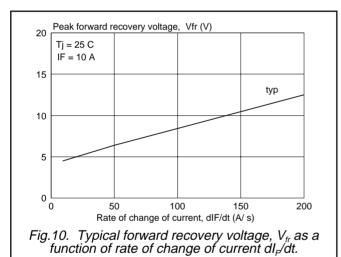


Fig.12. Typical and maximum forward characteristic $I_F = f(V_F)$; $T_i = 25^{\circ}C$ and $150^{\circ}C$.



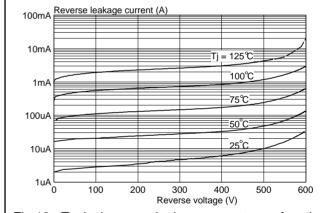
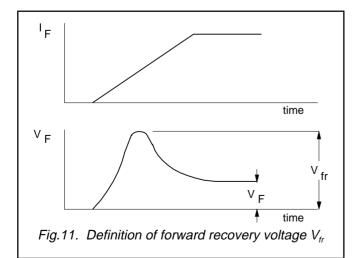


Fig.13. Typical reverse leakage current as a function of reverse voltage. $I_R = f(V_R)$; parameter T_j



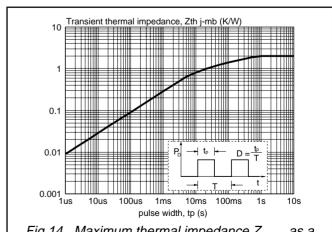
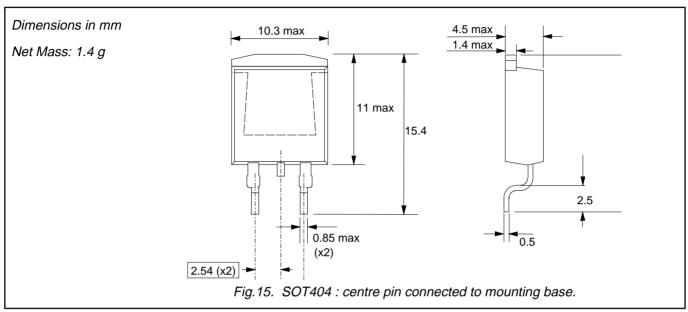


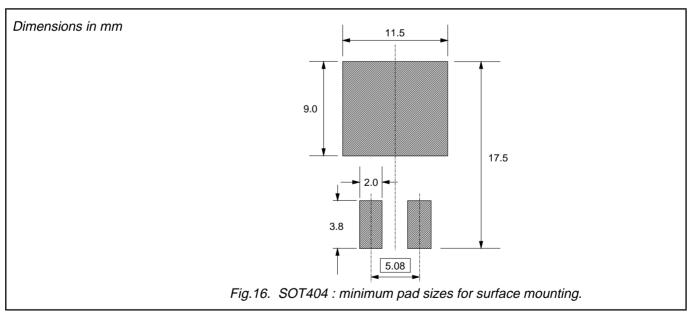
Fig.14. Maximum thermal impedance $Z_{th j-mb}$ as a function of pulse width.

BYC10B-600

MECHANICAL DATA



MOUNTING INSTRUCTIONS



Notes

1. Plastic meets UL94 V0 at 1/8".

Philips Semiconductors Product specification

Rectifier diode ultrafast, low switching loss

BYC10B-600

DEFINITIONS

Data sheet status				
Objective specification This data sheet contains target or goal specifications for product development.				
Preliminary specification This data sheet contains preliminary data; supplementary data may be published lat				
Product specification	This data sheet contains final product specifications.			
Limiting values				

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

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